Transistors

2SB1320

Silicon PNP epitaxial planar type

For low frequency power amplification Complementary to 2SD1991

■ Features

• Allowing supply with the radial taping

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-30	V	
Collector-emitter voltage (Base open)	V _{CEO}	-25	V	
Emitter-base voltage (Collector open)	V _{EBO}	-7	V	
Collector current	I_{C}	-100	mA	
Peak collector current	I_{CP}	-200	mA	
Collector power dissipation	P _C	400	mW	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

■ Package

- CodeMT-1-A1
- Pin Name
 - 1. Emitter
 - 2. Collector
 - 3. Base

■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \mu\text{A}, I_{\rm E} = 0$	-30	8	2.7	V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = -2 \text{ mA}, I_B = 0$	-25	70.		V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = -10 \mu\text{A}, I_C = 0$	9-7 c			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -20 \text{ V}, I_E = 0$			-1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CB} = -20 \text{ V}, I_{B} = 0$	9		-1	μΑ
Forward current transfer ratio *	h_{FE}	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$	160		460	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -100 \text{ mA}, I_{\rm B} = -10 \text{ mA}$			-1	V
Transition frequency	f_T	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		3.5		pF

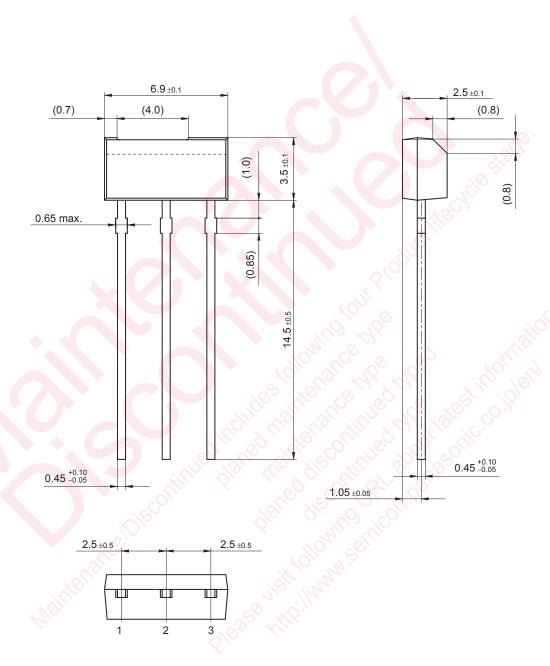
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	R	S
h_{FE}	160 to 260	210 to 340	290 to 460

2SB1320 Panasonic

MT-1-A1 Unit: mm



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